

LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND STRUCTURE THEREOF

Abstract of the Disclosure

5 An electronic package assembly where a low profile integrated circuit chip
package is soldered to an organic (e.g., epoxy resin) substrate, e.g., a printed circuit
board or card, the projecting conductive leads of the integrated circuit chip package and
the solder which substantially covers these leads (and respective conductors on the
substrate) having been substantially covered with ultraviolet photocured encapsulant
material (e.g., polymer resin) to provide reinforcement for the solder-lead connections.
10 The encapsulant material is dispensed about the solder and lead joints following solder
reflow and solidification so as to substantially surround the solder and any portions of
the leads not covered with solder.